

METHOD AND APPARATUS FOR MACHINING SUBSTRATE

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ABSTRACT OF THE DISCLOSURE

In a substrate machining method for machining a substrate, there are provided a substrate machining method in which a disk-like blade is rotated to cut the substrate from its one surface, and the cut surfaces of the substrate, which are positioned in the vicinity of the other surface of the substrate, are irradiated with laser light; and a substrate machining apparatus which carries out the substrate machining method. The entirety of the cut surfaces of the substrate may be irradiated with the laser light. The laser may be a YAG laser or a CO₂ laser. Further, a dicing tape may be adhered to the other surface of the substrate, and the laser light may be irradiated after cutting only the substrate and expanding the dicing tape. Modified layers are formed by an irradiation of the laser light, so that dice are prevented from being broken in an assembling operation of the dice.